

**TSM3400****SOT-23****Pin Definition:**

1. Gate
2. Source
3. Drain

PRODUCT SUMMARY

V_{DS} (V)	R_{D(on)}(mΩ)	I_D (A)
30	28 @ V _{GS} = 10V	5.8
	33 @ V _{GS} = 4.5V	5.0
	52 @ V _{GS} = 2.5V	4.0

Features

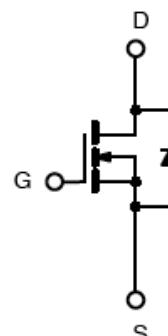
- Advance Trench Process Technology
- High Density Cell Design for Ultra Low On-resistance

Application

- Load Switch
- PA Switch

Ordering Information

Part No.	Package	Packing
TSM3400CX RF	SOT-23	3Kpcs / 7" Reel

Block Diagram

N-Channel MOSFET

Absolute Maximum Rating (Ta = 25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _{GS}	±12	V
Continuous Drain Current	I _D	5.8	A
Pulsed Drain Current	I _{DM}	30	A
Continuous Source Current (Diode Conduction) ^{a,b}	I _S	2.5	A
Maximum Power Dissipation @ Ta = 25°C	P _D	1.4	W
Operating Junction Temperature	T _J	+150	°C
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Thermal Performance

Parameter	Symbol	Limit	Unit
Junction to Foot Thermal Resistance	R _{θ_{JF}}	70	°C/W
Junction to Ambient Thermal Resistance (PCB mounted)	R _{θ_{JA}}	90	°C/W

Notes:

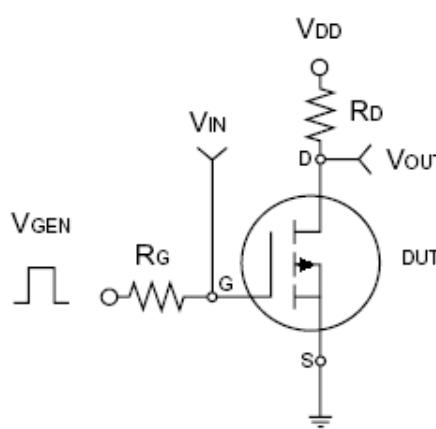
- a. Pulse width limited by the Maximum junction temperature
- b. Surface Mounted on FR4 Board, t ≤ 10 sec.

TSM3400**Electrical Specifications** ($T_a = 25^\circ\text{C}$ unless otherwise noted)

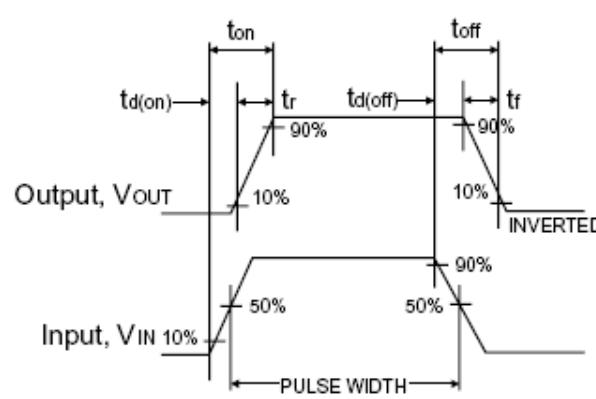
Parameter	Conditions	Symbol	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	BV_{DSS}	30	--	--	V
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	$V_{GS(\text{TH})}$	0.7	--	1.4	V
Gate Body Leakage	$V_{GS} = \pm 12\text{V}, V_{DS} = 0\text{V}$	I_{GSS}	--	--	± 100	nA
Zero Gate Voltage Drain Current	$V_{DS} = 24\text{V}, V_{GS} = 0\text{V}$	I_{DSS}	--	--	1.0	μA
On-State Drain Current	$V_{DS} = 5\text{V}, V_{GS} = 4.5\text{V}$	$I_{D(\text{ON})}$	20	--	--	A
Drain-Source On-State Resistance	$V_{GS} = 10\text{V}, I_D = 5.8\text{A}$	$R_{DS(\text{ON})}$	--	23	28	$\text{m}\Omega$
	$V_{GS} = 4.5\text{V}, I_D = 5\text{A}$		--	28	33	
	$V_{GS} = 2.5\text{V}, I_D = 4\text{A}$		--	43	52	
Forward Transconductance	$V_{DS} = 5\text{V}, I_D = 5\text{A}$	g_{fs}	10	15	--	S
Diode Forward Voltage	$I_S = 1.0\text{A}, V_{GS} = 0\text{V}$	V_{SD}	--	0.76	1.0	V
Dynamic^b						
Total Gate Charge	$V_{DS} = 15\text{V}, I_D = 5.8\text{A}, V_{GS} = 10\text{V}$	Q_g	--	9.7	12	nC
Gate-Source Charge		Q_{gs}	--	1.63	--	
Gate-Drain Charge		Q_{gd}	--	3.1	--	
Input Capacitance	$V_{DS} = 15\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$	C_{iss}	--	857	1030	pF
Output Capacitance		C_{oss}	--	97	--	
Reverse Transfer Capacitance		C_{rss}	--	71	--	
Switching^c						
Turn-On Delay Time	$V_{DD} = 15\text{V}, R_L = 1.8\Omega, I_D = 1\text{A}, V_{GEN} = 10\text{V}, R_G = 6\Omega$	$t_{d(on)}$	--	3.3	5	nS
Turn-On Rise Time		t_r	--	4.7	7	
Turn-Off Delay Time		$t_{d(off)}$	--	26	39	
Turn-Off Fall Time		t_f	--	4.1	6.2	

Notes:

- a. pulse test: PW $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- b. For DESIGN AID ONLY, not subject to production testing.
- c. Switching time is essentially independent of operating temperature.



Switching Test Circuit



Switching Waveforms